

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC3202xxxxZR-G

Typical Mass: 7.5 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.190	Silicon	25400	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	3.800	Copper	506700	7440-50-8
	0.070	Nickel	9400	7440-02-0
	0.021	Silver	2800	7440-22-4
	0.008	Chromium	1100	7440-47-3
	0.008	Tin	1000	7440-31-5
	0.006	Palladium	900	7440-05-3
	0.001	Gold	200	7440-57-5
Die attach	0.098	Silver	13100	7440-22-4
	0.017	Acryl resin	2300	—
	0.006	Bismaleimide resin	800	—
Bonding wire	0.035	Gold	4700	7440-57-5
Resin	3.036	Silica	404800	60676-86-0
	0.101	Epoxy resin	13500	—
	0.101	Phenol resin	13500	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."